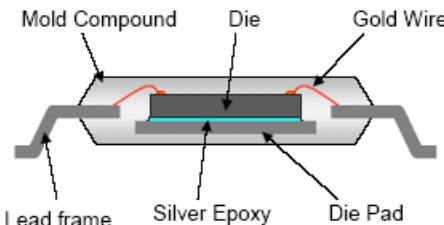


Material Declaration

Compliance Date: Jun./08/2022

RoHS Compliance: Yes

MSL: 3

Pin count /Package		44L 400mil TSOPII							
Model (Part) Number		AS6CE4016B-45ZIN							
Package Weight (mg)		436.31							
Composed parts	Purpose	Weight (mg)	%	ppm	Material	CAS No.	Weight (mg)	Material wt% of total Mass	Material wt% of Sub part
Chip	Wafer Circuit	13.79	3.16	31,606	Silicon (Si)	7440-21-3	13.790	3.161%	100.00%
Bonding Wire	Conductivity	0.86	0.20	1,971	Gold (Au)	7440-57-5	0.860	0.197%	100.00%
Die Attach	Conductivity	1.09	0.25	2,498	Silver (metal powder)	7440-22-4	0.839	0.192%	77.00%
					Acrylic resin	(Trade secret)	0.093	0.021%	8.50%
					Polybutadiene derivative	(Trade secret)	0.060	0.014%	5.50%
					Butadiene copolymer	(Trade secret)	0.011	0.002%	1.00%
					Epoxy resin	(Trade secret)	0.027	0.006%	2.50%
					Acrylate	(Trade secret)	0.044	0.010%	4.00%
					Peroxide	(Trade secret)	0.005	0.001%	0.50%
					Additive	(Trade secret)	0.011	0.002%	1.00%
Lead Frame	Base Metal	176.82	40.53	405,262	Copper (Cu)	7440-50-8	166.741	38.216%	94.30%
					Nickel (Ni)	7440-02-0	5.658	1.297%	3.20%
					Silicon (Si)	7440-21-3	1.282	0.294%	0.73%
					Magnesium (Mg)	7439-95-4	0.309	0.071%	0.18%
					Silver (Ag)	7440-22-4	2.829	0.648%	1.60%
Molding Compound	Chip Protection	234.2	53.68	536,774	Silica (SiO ₂)	60676-86-0	208.438	47.773%	89.00%
					Epoxy Resin (1)	(Trade secret)	7.026	1.610%	3.00%
					Epoxy Resin (2)	(Trade secret)	4.684	1.074%	2.00%
					Phenol Resin (1)	(Trade secret)	4.684	1.074%	2.00%
					Phenol Resin (2)	(Trade secret)	4.684	1.074%	2.00%
					Carbon Black (C)	1333-86-4	0.703	0.161%	0.30%
					Others	(Trade secret)	3.981	0.913%	1.70%
Plating of lead frame	Solder Plating	9.55	2.19	21,888	Tin (Sn)	7440-31-5	9.550	2.189%	100.00%